



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-05-04
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STF24N60M2	TSFP*MQ6HB82	A	SHENZHEN B/E	2016-05-04
Amount		UoM	Unit type	ST ECOPACK Grade
1900.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10-9.05-4.4	3	THROUGH HOLE	
Comment	TO 220 ISO FULL PACK IN LINE			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TSFP*MQGHB2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	11.280	mg	supplier	die	Silicon (Si)	7440-21-3		10.825	mg	959667	5698
				supplier	metallization	Aluminium (Al)	7429-90-5		0.219	mg	19413	115
				supplier	Passivation	Silicon Nitride	12033-89-5		0.052	mg	4610	27
				supplier	Passivation	Silicon Oxide	7631-86-9		0.077	mg	6826	41
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.005	mg	443	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.075	mg	6648	39
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.027	mg	2393	14
Leadframe	Copper & its alloys	1257.964	mg	supplier	alloy	Copper (Cu)	7440-50-8		1251.376	mg	994763	658619
				supplier	alloy	Iron (Fe)	7439-89-6		1.253	mg	996	659
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.376	mg	299	198
				supplier	metallization	Nickel (Ni)	7440-02-0		4.928	mg	3917	2594
				supplier	metallization	Phosphorus (P)	12185-10-3		0.031	mg	25	16
Soft solder	Solder	10.327	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	9.862	mg	954972	5191
				supplier	solder	Silver (Ag)	7440-22-4		0.258	mg	24983	136
				supplier	solder	Tin (Sn)	7440-31-5		0.207	mg	20045	109
Bonding wires	Other inorganic materials	1.562	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.561	mg	999360	822
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	640	1
Encapsulation	Other Organic Materials	612.505	mg	supplier	mold compound	Quartz	14808-60-7		428.753	mg	699999	225659
				supplier	mold compound	Silica, vitreous	60676-86-0		45.938	mg	75000	24178
				supplier	mold compound	Epoxy resin	25068-38-6		85.751	mg	140000	45132
				supplier	mold compound	phenol resin	29690-82-2		42.875	mg	69999	22566
				supplier	mold compound	metal hydroxide	21645-51-2		6.125	mg	10000	3224
Connections coating	Solder	6.362	mg	supplier	mold compound	carbon black	1333-86-4		3.063	mg	5002	1611
				supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348